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Kind regards,

Team Nexperia

# 74AHC257-Q100; 74AHCT257-Q100

Quad 2-input multiplexer; 3-state

Rev. 1 — 22 July 2013

Product data sheet

## 1. General description

The 74AHC257-Q100; 74AHCT257-Q100 is a high-speed Si-gate CMOS device and is pin compatible with Low-power Schottky TTL (LSTTL). It is specified in compliance with JEDEC standard No. 7-A.

The 74AHC257-Q100; 74AHCT257-Q100 has four identical 2-input multiplexers with 3-state outputs. They select 4 bits of data from two sources and a common data select input (S) controls them. The data inputs from source 0 (1I0 to 4I0), are selected when input S is LOW. The data inputs from source 1 (1I1 to 4I1) are selected when input S is HIGH. Data appears at the outputs (1Y to 4Y) in true (non-inverting) form from the selected inputs. The 74AHC257-Q100; 74AHCT257-Q100 is the logic implementation of a 4-pole 2-position switch. The logic levels applied to input S determine the position of the switch. The outputs are forced to a high-impedance OFF-state when  $\overline{OE}$  is HIGH.

The logic equations for the outputs are:

$$1Y = \overline{OE} \times (1I1 \times S + 1I0 \times \overline{S})$$

$$2Y = \overline{OE} \times (2I1 \times S + 2I0 \times \overline{S})$$

$$3Y = \overline{OE} \times (3I1 \times S + 3I0 \times \overline{S})$$

$$4Y = \overline{OE} \times (4I1 \times S + 4I0 \times \overline{S})$$

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

## 2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
  - ◆ Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$
- Balanced propagation delays
- All inputs have Schmitt-trigger actions
- Non-inverting data path
- Inputs accept voltages higher than  $V_{CC}$
- Input levels:
  - ◆ For 74AHC257-Q100: CMOS level
  - ◆ For 74AHCT257-Q100: TTL level



- ESD protection:
  - ◆ MIL-STD-883, method 3015 exceeds 2000 V
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V (C = 200 pF, R = 0 Ω)
- Multiple package options

### 3. Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
<b>74AHC257-Q100</b>				
74AHC257D-Q100	-40 °C to +125 °C	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
74AHC257PW-Q100	-40 °C to +125 °C	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1
<b>74AHCT257-Q100</b>				
74AHCT257D-Q100	-40 °C to +125 °C	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
74AHCT257PW-Q100	-40 °C to +125 °C	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm	SOT403-1

### 4. Functional diagram

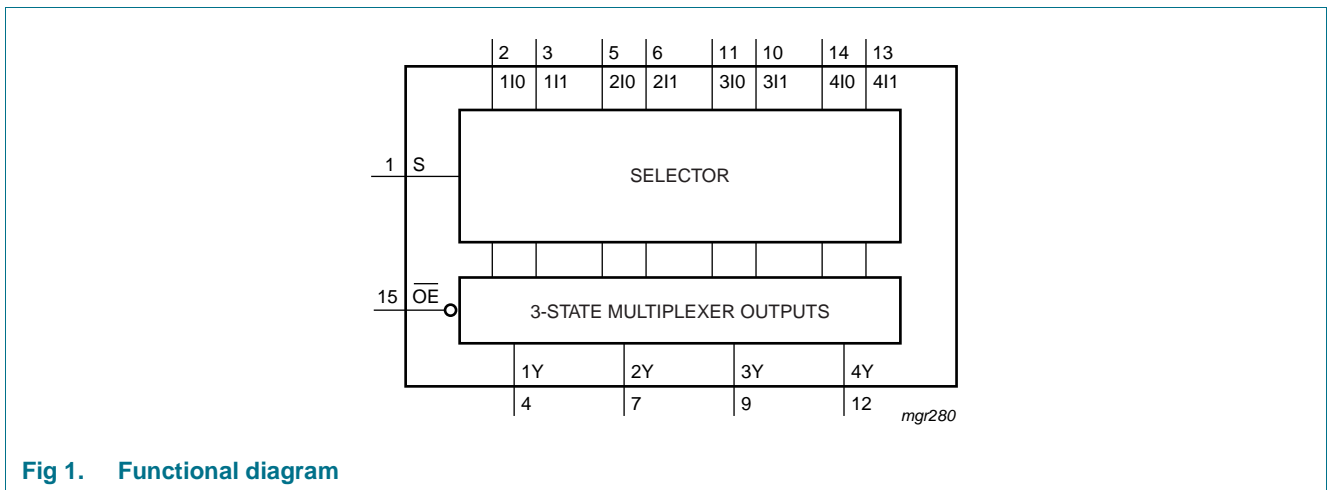


Fig 1. Functional diagram

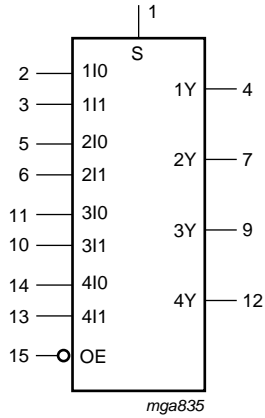


Fig 2. Logic symbol

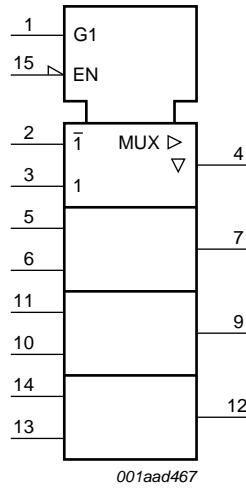


Fig 3. IEC logic symbol

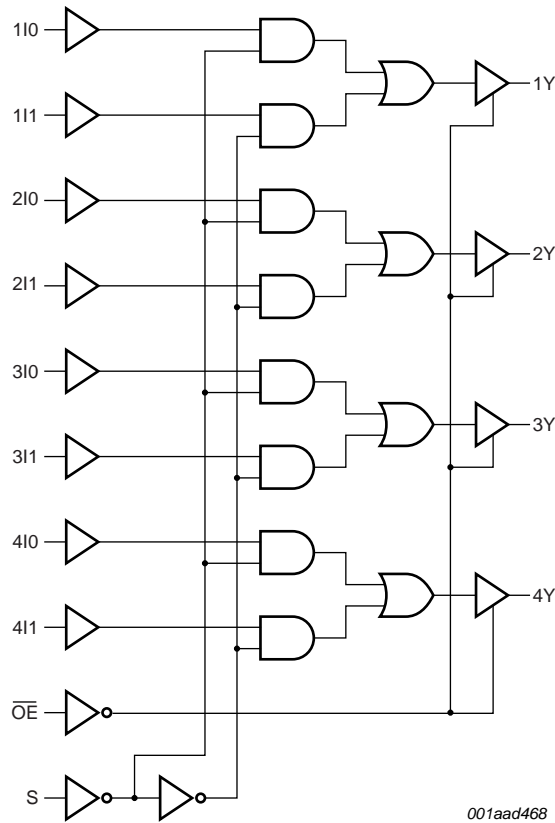


Fig 4. Logic diagram

## 5. Pinning information

### 5.1 Pinning

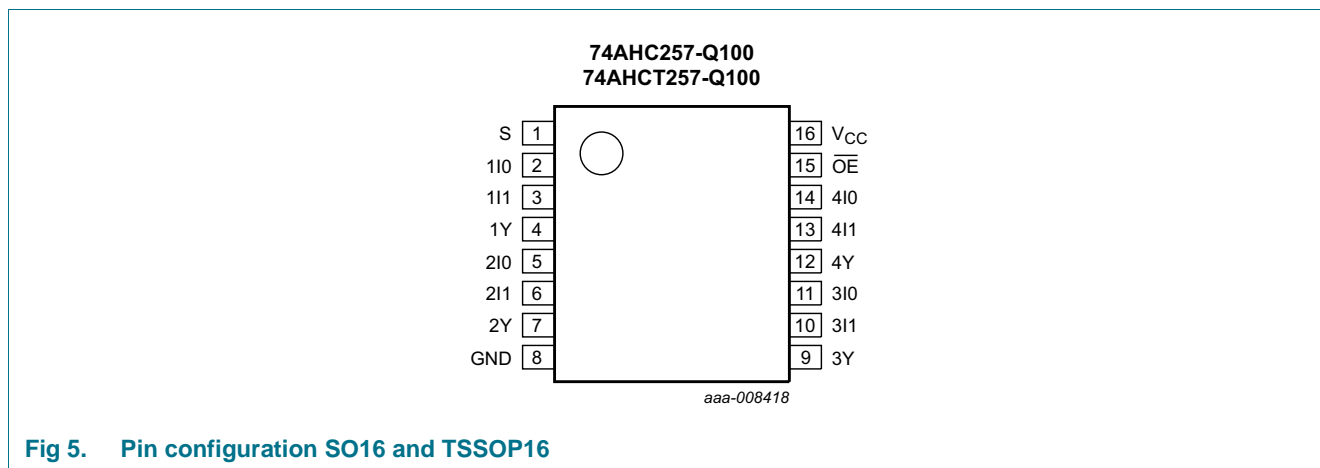


Fig 5. Pin configuration SO16 and TSSOP16

### 5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
S	1	common data select input
1I0	2	data input from source 0
1I1	3	data input from source 1
1Y	4	multiplexer output
2I0	5	data input from source 0
2I1	6	data input from source 1
2Y	7	multiplexer output
GND	8	ground (0 V)
3Y	9	multiplexer output
3I1	10	data input from source 1
3I0	11	data input from source 0
4Y	12	multiplexer output
4I1	13	data input from source 1
4I0	14	data input from source 0
$\overline{OE}$	15	output enable input (active LOW)
V <sub>CC</sub>	16	supply voltage

## 6. Functional description

Table 3. Function table<sup>[1]</sup>

Control		Input		Output
OE	S	nI0	nI1	nY
H	X	X	X	Z
L	H	X	L	L
		X	H	H
	L	L	X	L
		H	X	H

- [1] H = HIGH voltage level;  
 L = LOW voltage level;  
 X = don't care;  
 Z = high-impedance OFF-state.

## 7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+7.0	V
$V_I$	input voltage		-0.5	+7.0	V
$I_{IK}$	input clamping current	$V_I < -0.5$ V	[1] -20	-	mA
$I_{OK}$	output clamping current	$V_O < -0.5$ V or $V_O > V_{CC} + 0.5$ V	[1] -20	+20	mA
$I_O$	output current	$V_O = -0.5$ V to $(V_{CC} + 0.5$ V)	-25	+25	mA
$I_{CC}$	supply current		-	+75	mA
$I_{GND}$	ground current		-75	-	mA
$T_{stg}$	storage temperature		-65	+150	°C
$P_{tot}$	total power dissipation	$T_{amb} = -40$ °C to +125 °C	[2] -	500	mW

- [1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
 [2] For SO16 packages: above 70 °C the value of  $P_{tot}$  derates linearly at 8 mW/K.  
 For TSSOP16 packages: above 60 °C the value of  $P_{tot}$  derates linearly at 5.5 mW/K.

## 8. Recommended operating conditions

Table 5. Operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>74AHC257-Q100</b>						
$V_{CC}$	supply voltage		2.0	5.0	5.5	V
$V_I$	input voltage		0	-	5.5	V
$V_O$	output voltage		0	-	$V_{CC}$	V
$T_{amb}$	ambient temperature		-40	+25	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 3.0\text{ V to }3.6\text{ V}$	-	-	100	ns/V
		$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	-	-	20	ns/V
<b>74AHCT257-Q100</b>						
$V_{CC}$	supply voltage		4.5	5.0	5.5	V
$V_I$	input voltage		0	-	5.5	V
$V_O$	output voltage		0	-	$V_{CC}$	V
$T_{amb}$	ambient temperature		-40	+25	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$	-	-	20	ns/V

## 9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
<b>74AHC257-Q100</b>										
$V_{IH}$	HIGH-level input voltage	$V_{CC} = 2.0\text{ V}$	1.5	-	-	1.5	-	1.5	-	V
		$V_{CC} = 3.0\text{ V}$	2.1	-	-	2.1	-	2.1	-	V
		$V_{CC} = 5.5\text{ V}$	3.85	-	-	3.85	-	3.85	-	V
$V_{IL}$	LOW-level input voltage	$V_{CC} = 2.0\text{ V}$	-	-	0.5	-	0.5	-	0.5	V
		$V_{CC} = 3.0\text{ V}$	-	-	0.9	-	0.9	-	0.9	V
		$V_{CC} = 5.5\text{ V}$	-	-	1.65	-	1.65	-	1.65	V
$V_{OH}$	HIGH-level output voltage	$V_I = V_{IH}$ or $V_{IL}$								
		$I_O = -50\ \mu\text{A}; V_{CC} = 2.0\text{ V}$	1.9	2.0	-	1.9	-	1.9	-	V
		$I_O = -50\ \mu\text{A}; V_{CC} = 3.0\text{ V}$	2.9	3.0	-	2.9	-	2.9	-	V
		$I_O = -50\ \mu\text{A}; V_{CC} = 4.5\text{ V}$	4.4	4.5	-	4.4	-	4.4	-	V
		$I_O = -4.0\text{ mA}; V_{CC} = 3.0\text{ V}$	2.58	-	-	2.48	-	2.40	-	V
	$I_O = -8.0\text{ mA}; V_{CC} = 4.5\text{ V}$	3.94	-	-	3.80	-	3.70	-	V	
$V_{OL}$	LOW-level output voltage	$V_I = V_{IH}$ or $V_{IL}$								
		$I_O = 50\ \mu\text{A}; V_{CC} = 2.0\text{ V}$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 50\ \mu\text{A}; V_{CC} = 3.0\text{ V}$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 50\ \mu\text{A}; V_{CC} = 4.5\text{ V}$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 4.0\text{ mA}; V_{CC} = 3.0\text{ V}$	-	-	0.36	-	0.44	-	0.55	V
	$I_O = 8.0\text{ mA}; V_{CC} = 4.5\text{ V}$	-	-	0.36	-	0.44	-	0.55	V	

**Table 6. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
$I_I$	input leakage current	$V_I = 5.5 \text{ V}$ or GND; $V_{CC} = 0 \text{ V}$ to 5.5 V	-	-	0.1	-	1.0	-	2.0	$\mu\text{A}$
$I_{OZ}$	OFF-state output current	$V_I = V_{IH}$ or $V_{IL}$ ; $V_O = V_{CC}$ or GND; $V_{CC} = 5.5 \text{ V}$	-	-	$\pm 0.25$	-	$\pm 2.5$	-	$\pm 10.0$	$\mu\text{A}$
$I_{CC}$	supply current	$V_I = V_{CC}$ or GND; $I_O = 0 \text{ A}$ ; $V_{CC} = 5.5 \text{ V}$	-	-	4.0	-	40	-	80	$\mu\text{A}$
$C_I$	input capacitance	$V_I = V_{CC}$ or GND	-	3	10	-	10	-	10	pF
$C_O$	output capacitance		-	4	-	-	-	-	-	pF

**74AHCT257-Q100**

$V_{IH}$	HIGH-level input voltage	$V_{CC} = 4.5 \text{ V}$ to 5.5 V	2.0	-	-	2.0	-	2.0	-	V
$V_{IL}$	LOW-level input voltage	$V_{CC} = 4.5 \text{ V}$ to 5.5 V	-	-	0.8	-	0.8	-	0.8	V
$V_{OH}$	HIGH-level output voltage	$V_I = V_{IH}$ or $V_{IL}$ ; $V_{CC} = 4.5 \text{ V}$								
		$I_O = -50 \mu\text{A}$	4.4	4.5	-	4.4	-	4.4	-	V
		$I_O = -8.0 \text{ mA}$	3.94	-	-	3.80	-	3.70	-	V
$V_{OL}$	LOW-level output voltage	$V_I = V_{IH}$ or $V_{IL}$ ; $V_{CC} = 4.5 \text{ V}$								
		$I_O = 50 \mu\text{A}$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 8.0 \text{ mA}$	-	-	0.36	-	0.44	-	0.55	V
$I_I$	input leakage current	$V_I = 5.5 \text{ V}$ or GND; $V_{CC} = 0 \text{ V}$ to 5.5 V	-	-	0.1	-	1.0	-	2.0	$\mu\text{A}$
$I_{OZ}$	OFF-state output current	$V_I = V_{IH}$ or $V_{IL}$ ; $V_O = V_{CC}$ or GND per input pin; other inputs at $V_{CC}$ or GND; $I_O = 0 \text{ A}$ ; $V_{CC} = 5.5 \text{ V}$	-	-	$\pm 0.25$	-	$\pm 2.5$	-	$\pm 10.0$	$\mu\text{A}$
$I_{CC}$	supply current	$V_I = V_{CC}$ or GND; $I_O = 0 \text{ A}$ ; $V_{CC} = 5.5 \text{ V}$	-	-	4.0	-	40	-	80	$\mu\text{A}$
$\Delta I_{CC}$	additional supply current	per input pin; $V_I = V_{CC} - 2.1 \text{ V}$ ; other pins at $V_{CC}$ or GND; $I_O = 0 \text{ A}$ ; $V_{CC} = 4.5 \text{ V}$ to 5.5 V	-	-	1.35	-	1.5	-	1.5	mA
$C_I$	input capacitance	$V_I = V_{CC}$ or GND	-	3	10	-	10	-	10	pF
$C_O$	output capacitance		-	4	-	-	-	-	-	pF



## 10. Dynamic characteristics

**Table 7. Dynamic characteristics**

Voltages are referenced to GND (ground = 0 V); for test circuit, see [Figure 8](#).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	Min	Max	
<b>74AHC257-Q100</b>										
t <sub>pd</sub>	propagation delay	nI0, nI1 to nY; see <a href="#">Figure 6</a> <sup>[2]</sup>								
		V <sub>CC</sub> = 3.0 V to 3.6 V								
		C <sub>L</sub> = 15 pF	-	4.2	9.3	1.0	11.0	1.0	12.0	ns
		C <sub>L</sub> = 50 pF	-	6.0	12.8	1.0	14.5	1.0	16.0	ns
		V <sub>CC</sub> = 4.5 V to 5.5 V								
		C <sub>L</sub> = 15 pF	-	2.9	5.9	1.0	7.0	1.0	7.5	ns
		C <sub>L</sub> = 50 pF	-	4.2	7.9	1.0	9.0	1.0	11.5	ns
		S to nY; see <a href="#">Figure 6</a> <sup>[2]</sup>								
		V <sub>CC</sub> = 3.0 V to 3.6 V								
		C <sub>L</sub> = 15 pF	-	5.2	11.0	1.0	13.0	1.0	14.0	ns
		C <sub>L</sub> = 50 pF	-	7.4	14.5	1.0	16.5	1.0	18.5	ns
		t <sub>en</sub>	enable time	$\overline{\text{OE}}$ to nY; see <a href="#">Figure 7</a> <sup>[3]</sup>						
V <sub>CC</sub> = 3.0 V to 3.6 V										
C <sub>L</sub> = 15 pF	-			4.5	10.5	1.0	12.5	1.0	13.5	ns
C <sub>L</sub> = 50 pF	-			6.4	14.0	1.0	16.0	1.0	17.5	ns
V <sub>CC</sub> = 4.5 V to 5.5 V										
C <sub>L</sub> = 15 pF	-			3.2	6.8	1.0	8.0	1.0	8.5	ns
t <sub>dis</sub>	disable time	$\overline{\text{OE}}$ to nY; see <a href="#">Figure 7</a> <sup>[4]</sup>								
		V <sub>CC</sub> = 3.0 V to 3.6 V								
		C <sub>L</sub> = 15 pF	-	5.1	9.5	1.0	11.0	1.0	11.5	ns
		C <sub>L</sub> = 50 pF	-	7.2	12.0	1.0	13.5	1.0	14.5	ns
		V <sub>CC</sub> = 4.5 V to 5.5 V								
		C <sub>L</sub> = 15 pF	-	3.4	6.5	1.0	7.0	1.0	8.5	ns
C <sub>PD</sub>	power dissipation capacitance	f <sub>i</sub> = 1 MHz; V <sub>I</sub> = GND to V <sub>CC</sub> <sup>[5]</sup>								
		4 outputs switching via input S	-	45	-	-	-	-	pF	
		1 output switching via input I	-	15	-	-	-	-	pF	

**Table 7. Dynamic characteristics ...continued**

*Voltages are referenced to GND (ground = 0 V); for test circuit, see [Figure 8](#).*

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	Min	Max	
<b>74AHCT257-Q100; V<sub>CC</sub> = 4.5 V to 5.5 V</b>										
t <sub>pd</sub>	propagation delay	nI0, nI1 to nY; see <a href="#">Figure 6</a> <sup>[2]</sup>	-	3.7	6.5	1.0	8.0	1.0	9.0	ns
		C <sub>L</sub> = 15 pF	-	3.7	6.5	1.0	8.0	1.0	9.0	ns
		C <sub>L</sub> = 50 pF	-	4.9	8.5	1.0	10.0	1.0	11.0	ns
		S to nY; see <a href="#">Figure 6</a> <sup>[2]</sup>	-	5.1	9.0	1.0	10.5	1.0	11.5	ns
		C <sub>L</sub> = 50 pF	-	6.4	10.5	1.0	12.5	1.0	13.5	ns
t <sub>en</sub>	enable time	$\overline{OE}$ to nY; see <a href="#">Figure 7</a> <sup>[3]</sup>	-	3.9	8.0	1.0	9.0	1.0	10.0	ns
		C <sub>L</sub> = 15 pF	-	3.9	8.0	1.0	9.0	1.0	10.0	ns
		C <sub>L</sub> = 50 pF	-	5.1	10.0	1.0	11.0	1.0	12.0	ns
t <sub>dis</sub>	disable time	$\overline{OE}$ to nY; see <a href="#">Figure 7</a> <sup>[4]</sup>	-	4.5	7.5	1.0	8.0	1.0	8.5	ns
		C <sub>L</sub> = 15 pF	-	4.5	7.5	1.0	8.0	1.0	8.5	ns
		C <sub>L</sub> = 50 pF	-	6.5	9.5	1.0	10.5	1.0	11.5	ns
C <sub>PD</sub>	power dissipation capacitance	f <sub>i</sub> = 1 MHz; V <sub>I</sub> = GND to V <sub>CC</sub> <sup>[5]</sup>	-	51	-	-	-	-	-	pF
		4 outputs switching via input S	-	51	-	-	-	-	-	pF
		1 output switching via input I	-	15	-	-	-	-	-	pF

[1] Typical values are measured at nominal supply voltage (V<sub>CC</sub> = 3.3 V and V<sub>CC</sub> = 5.0 V).

[2] t<sub>pd</sub> is the same as t<sub>PLH</sub> and t<sub>PHL</sub>.

[3] t<sub>en</sub> is the same as t<sub>PZL</sub> and t<sub>PZH</sub>.

[4] t<sub>dis</sub> is the same as t<sub>PLZ</sub> and t<sub>PHZ</sub>.

[5] C<sub>PD</sub> is used to determine the dynamic power dissipation (P<sub>D</sub> in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f<sub>i</sub> = input frequency in MHz;

f<sub>o</sub> = output frequency in MHz;

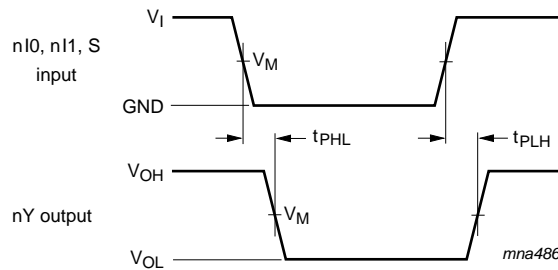
C<sub>L</sub> = output load capacitance in pF;

V<sub>CC</sub> = supply voltage in V;

N = number of inputs switching;

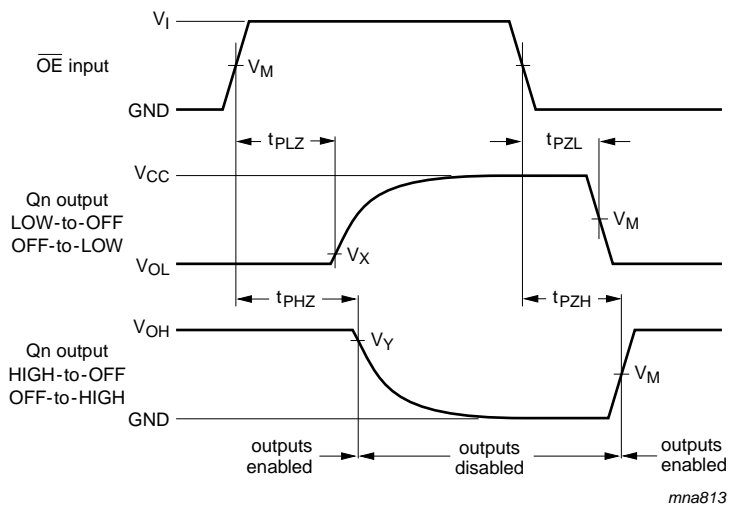
∑(C<sub>L</sub> × V<sub>CC</sub><sup>2</sup> × f<sub>o</sub>) = sum of the outputs.

11. Waveforms



Measurement points are given in [Table 8](#).  
 $V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

**Fig 6. Data inputs and common data select input to output propagation delays**

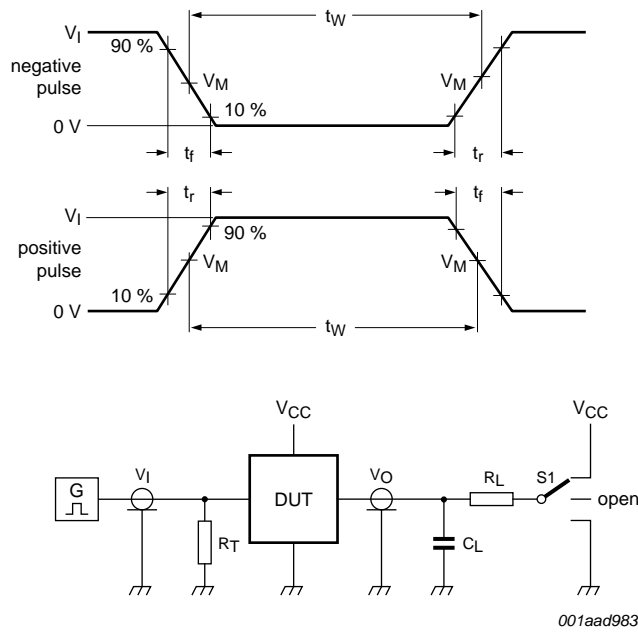


Measurement points are given in [Table 8](#).  
 $V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

**Fig 7. Enable and disable times**

**Table 8. Measurement points**

Type	Input	Output		
	$V_M$	$V_M$	$V_X$	$V_Y$
74AHC257-Q100	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$	$V_{OL} + 0.3 \text{ V}$	$V_{OH} - 0.3 \text{ V}$
74AHCT257-Q100	1.5 V	$0.5 \times V_{CC}$	$V_{OL} + 0.3 \text{ V}$	$V_{OH} - 0.3 \text{ V}$



Test data is given in [Table 9](#).

Definitions test circuit:

$R_T$  = termination resistance should be equal to output impedance  $Z_o$  of the pulse generator.

$C_L$  = load capacitance including jig and probe capacitance.

$R_L$  = load resistance.

S1 = test selection switch.

**Fig 8. Test circuitry for measuring switching times**

**Table 9. Test data**

Type	Input		Load		S1 position		
	$V_I$	$t_r, t_f$	$C_L$	$R_L$	$t_{PHL}, t_{PLH}$	$t_{PZH}, t_{PHZ}$	$t_{PZL}, t_{PLZ}$
74AHC257-Q100	$V_{CC}$	$\leq 3.0$ ns	15 pF, 50 pF	1 k $\Omega$	open	GND	$V_{CC}$
74AHCT257-Q100	3.0 V	$\leq 3.0$ ns	15 pF, 50 pF	1 k $\Omega$	open	GND	$V_{CC}$

12. Package outline

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1

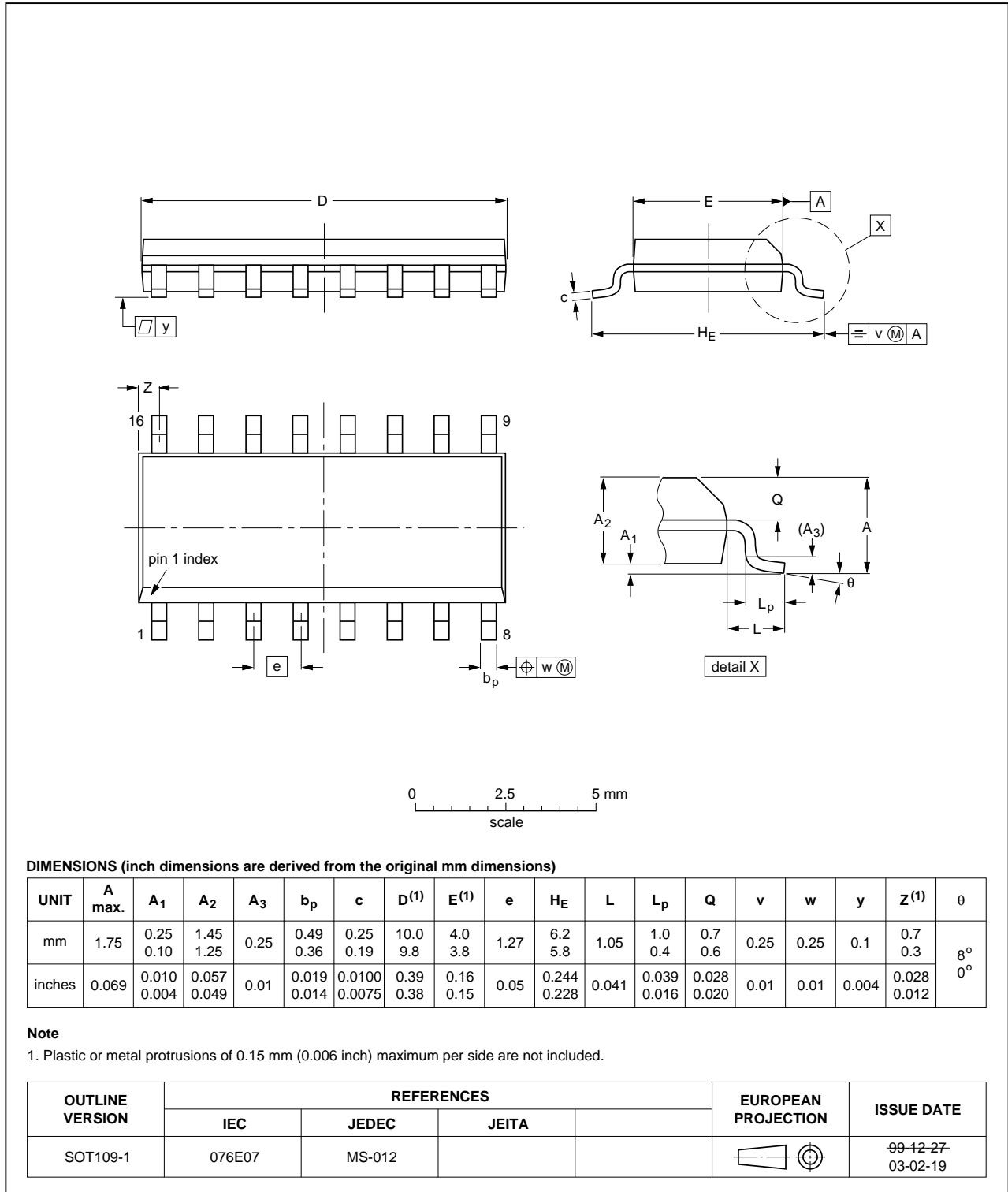


Fig 9. Package outline SOT109-1 (SO16)

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm

SOT403-1

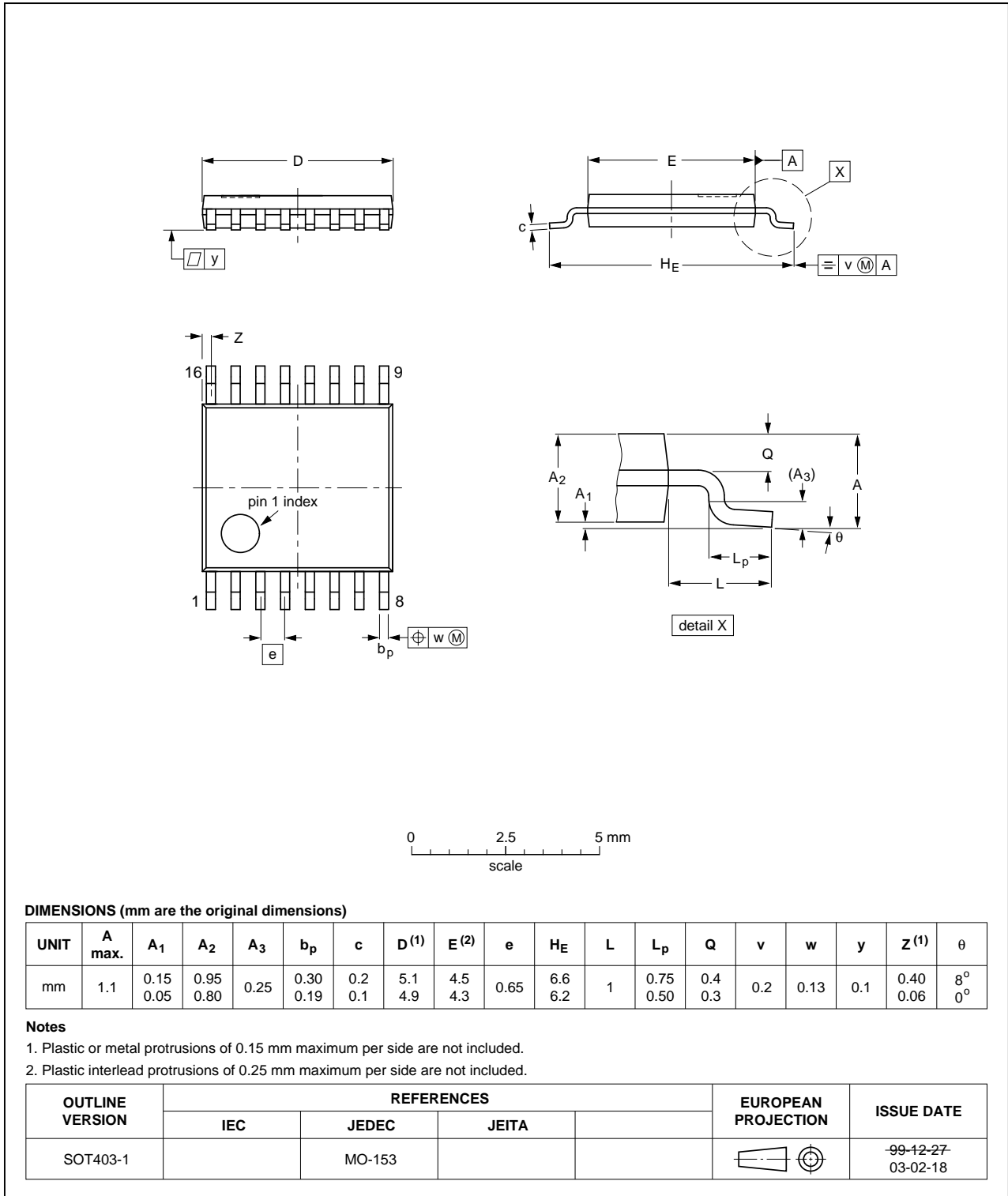


Fig 10. Package outline SOT403-1 (TSSOP16)

## 13. Abbreviations

Table 10. Abbreviations

Acronym	Description
CDM	Charged Device Model
CMOS	Complementary Metal-Oxide Semiconductor
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
MIL	Military
TTL	Transistor-Transistor Logic

## 14. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74AHC_AHCT257_Q100 v.1	20130722	Product data sheet	-	-

## 15. Legal information

### 15.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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